



# 100% Material Declaration Data Sheet CS144

PK149 (v1.2) September 28, 2006

Material Declaration Data Sheet

**Average Weight: 0.3 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					<b>0.01818</b>	<b>6.06%</b>
	Silicon	7440-21-3	100.00		0.01818	
Die Attach Material					<b>0.00099</b>	<b>0.33%</b>
	Silver	7440-22-4	52.00		0.0005148	
	Resin (EP)	Trade Secret	48.00		0.0004752	
Encapsulant					<b>0.15591</b>	<b>51.97%</b>
	Epoxy Resins	Trade Secret	6.00		0.0093546	
	Phenolic Resins	Trade Secret	6.00		0.0093546	
	Carbon Black	1333-86-4	0.50	Color	0.00077955	
	Silica	60676-86-0	84.00		0.1309644	
	Bismuth	7440-69-9	Max 1.00		0.0015591	
	Metal Hydroxide	Trade Secret	2.50		0.00389775	
Tape					<b>0.01794</b>	<b>5.98%</b>
	Polymide	Trade Secret	41.51		0.007446894	
	Adhesive	Trade Secret	58.49		0.010493106	
Metal Layers					<b>0.03285</b>	<b>10.95%</b>
	Copper	7440-50-8	88.32		0.02901312	
	Nickel	7440-02-0	7.90		0.00259515	
	Gold	7440-57-5	3.78		0.00124173	
Bond Wire					<b>0.00261</b>	<b>0.87%</b>
	Gold	7440-57-5	100.00		0.00261	
Solder Balls					<b>0.07152</b>	<b>23.84%</b>
	Tin	7440-31-5	63.00		0.0450576	
	Lead	7439-92-1	37.00		0.0264624	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
4/06/06	1.0	Initial release.
7/21/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.